



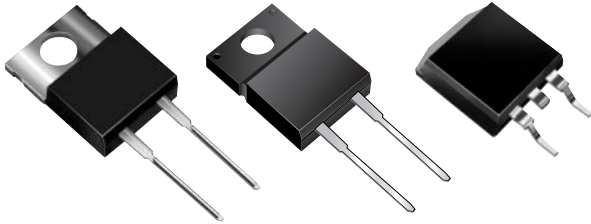
BY229, BY229X, BY229B Series

New Product

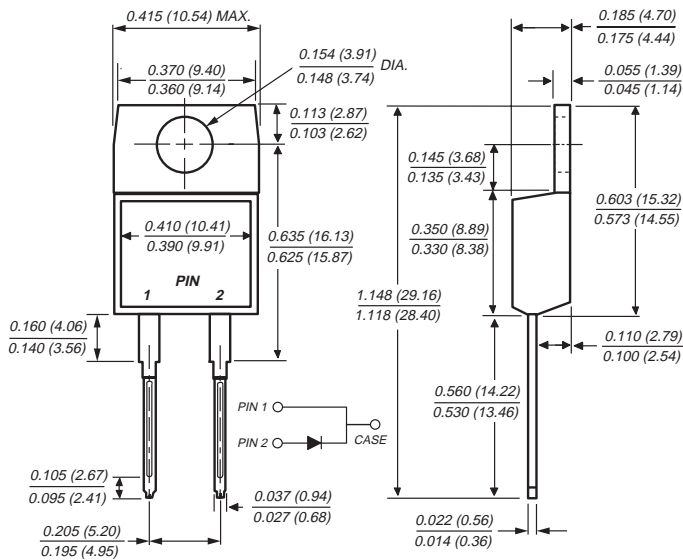
Vishay Semiconductors
formerly General Semiconductor

Fast Switching Plastic Rectifier

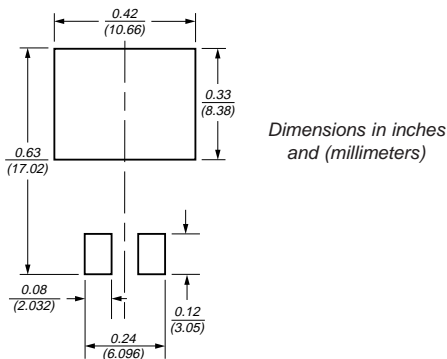
Reverse Voltage 200 to 800V
Forward Current 8.0A



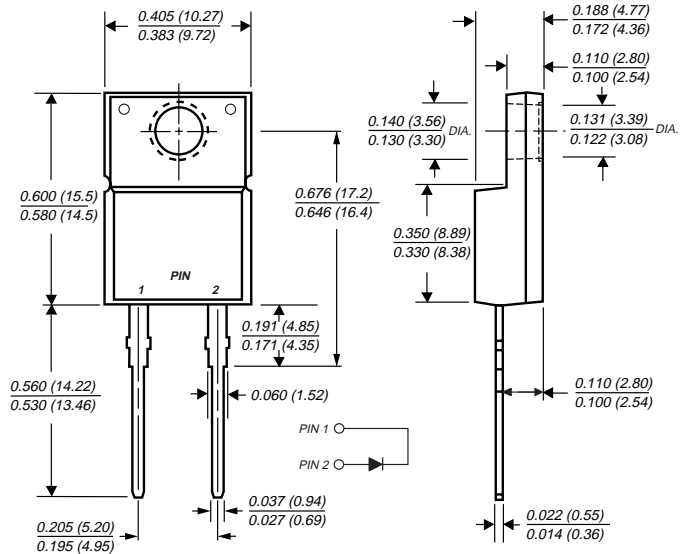
TO-220AC (BY229 Series)



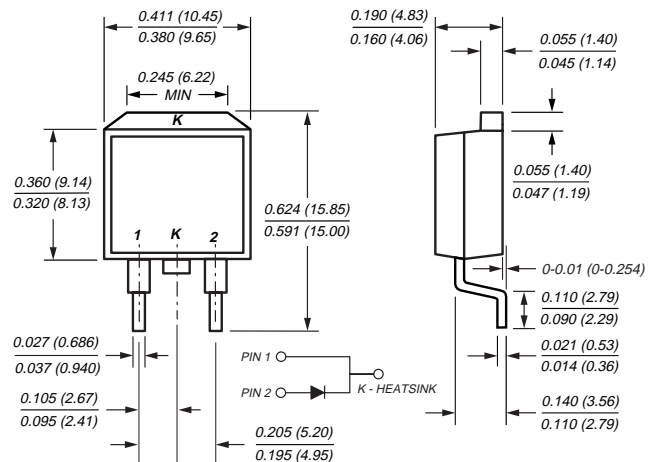
Mounting Pad Layout TO-263AB



ITO-220AC (BY229X Series)



TO-263AB (BY229B Series)



Features

- Plastic package has Underwriters Laboratories Flammability Classification 94V-0
- Glass passivated chip junction
- Low leakage, high voltage
- High surge current capability
- Superfast recovery time, for high efficiency
- High temperature soldering guaranteed: 250°C, 0.25" (6.35mm) from case for 10 seconds

Mechanical Data

- Case:** JEDEC TO-220AC, ITO-220AC and TO-263AB plastic body over passivated chip
- Terminals:** Plated leads, solderable per MIL-STD-750, Method 2026
- Polarity:** As marked
- Mounting Position:** Any
- Weight:** 0.064 oz., 1.81 g
- Mounting Torque:** 10 in-lbs maximum

BY229, BY229X, BY229B Series

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Maximum Ratings (T_C = 25°C unless otherwise noted)

Parameter	Symbol	BY229-200	BY229-400	BY229-600	BY229-800	Unit
Maximum recurrent peak reverse voltage	V _{RRM}	200	400	600	800	V
Maximum RMS voltage	V _{RMS}	140	280	420	560	V
Maximum DC blocking voltage	V _{DC}	200	400	600	800	V
Maximum average forward rectified current at T _C =100°C	I _{F(AV)}	8.0				A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	100				A
Maximum slope of reverse recovery current I _F =2.0A, V _R =30V, di/dt=20A/μs	di/dt	60				A/μs
Operating junction and storage temperature range	T _J , T _{STG}	-40 to +150				°C
RMS Isolation voltage from terminals to heatsink with t = 1 second, RH ≤ 30% (BY229X only)	V _{ISOL}	4500 (Note 1) 3500 (Note 2) 1500 (Note 3)				V

Electrical Characteristics (T_C = 25°C unless otherwise noted)

Parameter	Symbol	BY229-200	BY229-400	BY229-600	BY229-800	Unit
Maximum instantaneous forward voltage at 20A	V _F	1.85				V
Maximum DC reverse current at T _J = 25°C at rated DC blocking voltage T _J = 125°C	I _R	10 300				μA
Maximum reverse recovery time at I _F =1.0A, V _R =30V, di/dt=50A/μs, I _{rr} =10% I _{RM}	t _{rr}	145				ns
Maximum recovered stored charge (Note 2) I _F =2.0A, V _R =30V, di/dt=20A/μs	Q _{rr}	700				nC

Thermal Characteristics (T_C = 25°C unless otherwise noted)

Parameter	Symbol	BY229	BY229X	BY229B	Unit
Typical thermal resistance, junction to case	R _{θJC}	2.0	4.8	2.0	°C/W
Typical thermal resistance, junction to air	R _{θJA}	20	—	20	°C/W

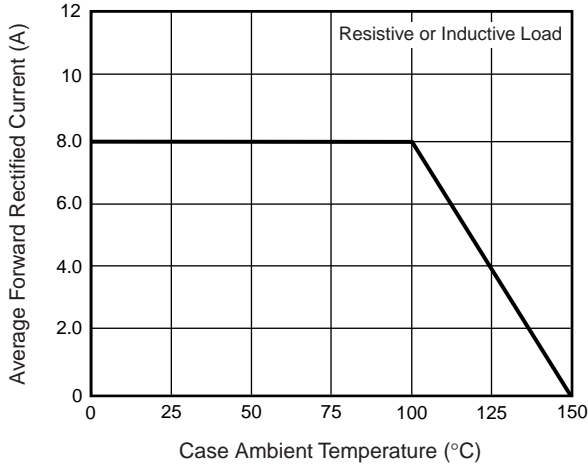
Notes:

- (1) Clip mounting, where lead does not overlap heatsink with 0.110" offset.
- (2) Clip mounting, where leads do overlap heatsink.
- (3) Screw mounting with 4-40 screw, where washer diameter is ≤ 4.9 mm (0.19").

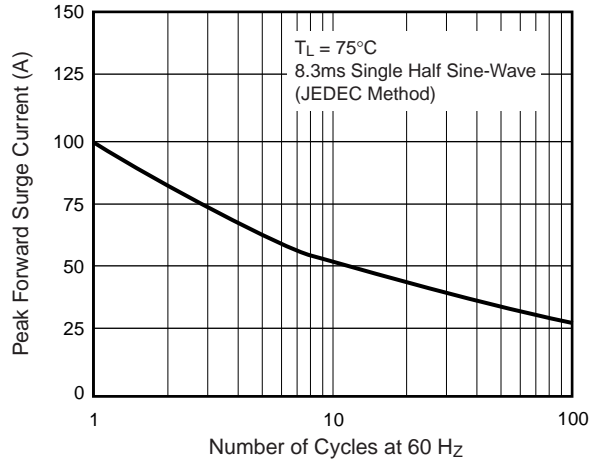


Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

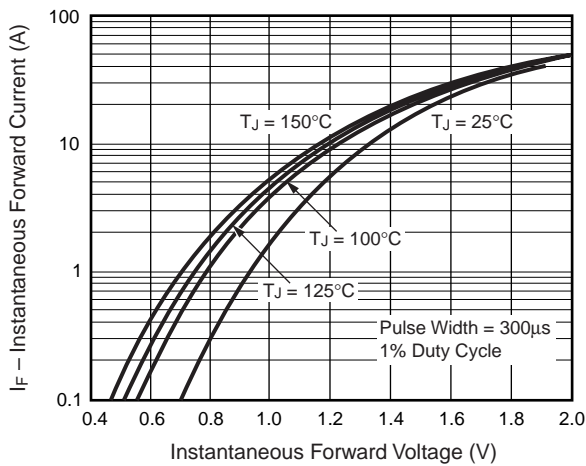
Forward Current Derating Curve



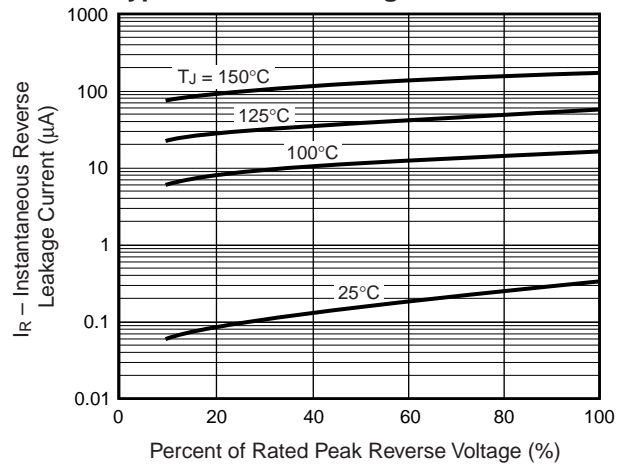
Maximum Non-Repetitive Peak Forward Surge Current



Typical Instantaneous Forward Characteristics



Typical Reverse Leakage Characteristics



Typical Junction Capacitance

